

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of )  
Chi Keung LEE et al ) Group Art Unit: Unassigned  
Application No.: Unassigned ) Examiner: Unassigned  
Filed: January 15, 2002 )  
For: A METHOD OF FORMING A )  
DUAL-INTERFACE IC CARD AND )  
A CARD FORMED OF SUCH A )  
METHOD )

**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination and the calculation of filing fees, kindly amend the above-identified application as follows.

**IN THE CLAIMS:**

3. (Amended) A method according to Claim 1 wherein said antenna coil is secured with said integrated circuit by soldering or thermo compression bonding.
4. (Amended) A method according to Claim 1 further including a step (f) of positioning a first part of said integrated circuit within said first cavity.

7. (Amended) A method according to Claim 5 wherein said second cavity is narrower than said first cavity.

8. (Amended) A method according to Claim 1 including a step (h) of applying an adhesive material on at least part of said first cavity.

9. (Amended) A method according to Claim 1 further including a step (i) of removing an insulating coating from said end(s) of said antenna coil.

Add the following new claims:

12. (New) A method according to Claim 2 wherein said antenna coil is secured with said integrated circuit by soldering or thermo compression bonding.

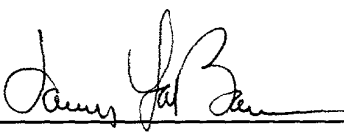
13. (New) A method according to Claim 6 wherein said second cavity is narrower than said first cavity.

**REMARKS**

Entry of the foregoing amendments is respectfully requested. These amendments are intended to eliminate the multiple dependency of the claims.

Respectfully submitted,

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**Attachment to Preliminary Amendment dated January 15, 2002**

**Marked-up Claims 3, 4, 7-9**

3. (Amended) A method according to Claim 1 [or 2] wherein said antenna coil is secured with said integrated circuit by soldering or thermo compression bonding.

4. (Amended) A method according to [any of the preceding claims] Claim 1 further including a step (f) of positioning a first part of said integrated circuit within said first cavity.

7. (Amended) A method according to Claim 5 [or 6] wherein said second cavity is narrower than said first cavity.

8. (Amended) A method according to [any of the preceding claims] Claim 1 including a step (h) of applying an adhesive material on at least part of said first cavity.

9. (Amended) A method according to [any of the preceding claims] Claim 1 further including a step (i) of removing an insulating coating from said end(s) of said antenna coil.